

# GB25MPS17-247

1700 V SiC MPS™ Diode



## Silicon Carbide Schottky Diode

|                                     |   |        |
|-------------------------------------|---|--------|
| $V_{RRM}$                           | = | 1700 V |
| $I_F$ ( $T_C = 135^\circ\text{C}$ ) | = | 55 A   |
| $Q_C$                               | = | 103 nC |

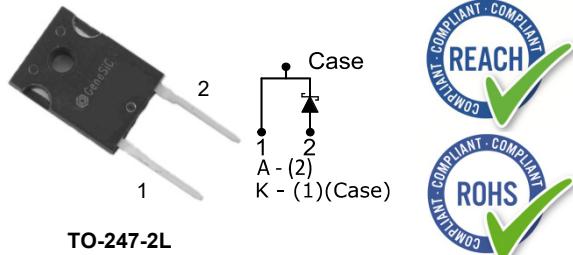
### Features

- High Avalanche (UIS) Capability
- Enhanced Surge Current Capability
- Superior Figure of Merit  $Q_C/I_F$
- Low Thermal Resistance
- 175 °C Maximum Operating Temperature
- Temperature Independent Switching Behavior
- Positive Temperature Coefficient of  $V_F$
- Extremely Fast Switching Speeds

### Advantages

- Low Standby Power Losses
- Improved Circuit Efficiency (Lower Overall Cost)
- Low Switching Losses
- Ease of Parallelizing without Thermal Runaway
- Smaller Heat Sink Requirements
- Low Reverse Recovery Current
- Low Device Capacitance
- Low Reverse Leakage Current

### Package



### Applications

- Wind Energy Converters
- Solar Inverters
- Motor Drives
- Freewheeling / Anti-parallel Diode in Inverters
- AC-DC and DC-DC Power Converters
- Switched Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Pulsed Power

### Absolute Maximum Ratings (At $T_C = 25^\circ\text{C}$ Unless Otherwise Stated)

| Parameter   | Symbol         | Conditions  | Values          | Unit                 |
|---|----------------|---|-----------------|----------------------|
| Repetitive Peak Reverse Voltage                           | $V_{RRM}$      |   | 1700            | V                    |
| Continuous Forward Current                                | $I_F$          | $T_C = 25^\circ\text{C}, D = 1$<br>$T_C = 135^\circ\text{C}, D = 1$<br>$T_C = 165^\circ\text{C}, D = 1$ | 110<br>55<br>25 | A                    |
| Non-Repetitive Peak Forward Surge Current, Half Sine Wave | $I_{F,SM}$     | $T_C = 25^\circ\text{C}, t_P = 10 \text{ ms}$<br>$T_C = 150^\circ\text{C}, t_P = 10 \text{ ms}$         | 115<br>89       | A                    |
| Repetitive Peak Forward Surge Current, Half Sine Wave     | $I_{F,RM}$     | $T_C = 25^\circ\text{C}, t_P = 10 \text{ ms}$<br>$T_C = 150^\circ\text{C}, t_P = 10 \text{ ms}$         | 56<br>38        | A                    |
| Non-Repetitive Peak Forward Surge Current                 | $I_{F,max}$    | $T_C = 25^\circ\text{C}, t_P = 10 \mu\text{s}$  | 680             | A                    |
| $\int i^2 dt$   | $\int i^2 dt$  | $T_C = 25^\circ\text{C}, t_P = 10 \text{ ms}$   | 66              | $\text{A}^2\text{s}$ |
| Non-Repetitive Avalanche Energy                           | $E_{AS}$       | $L = 0.6 \text{ mH}, I_{AS} = 25 \text{ A}$   | 180             | mJ                   |
| Diode Ruggedness  | $dV/dt$        | $V_R = 0 \sim 960 \text{ V}$  | 100             | V/ns                 |
| Power Dissipation   | $P_{tot}$      | $T_C = 25^\circ\text{C}$  | 843             | W                    |
| Operating and Storage Temperature                         | $T_j, T_{stg}$ |   | -55 to 175      | °C                   |



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## Electrical Characteristics

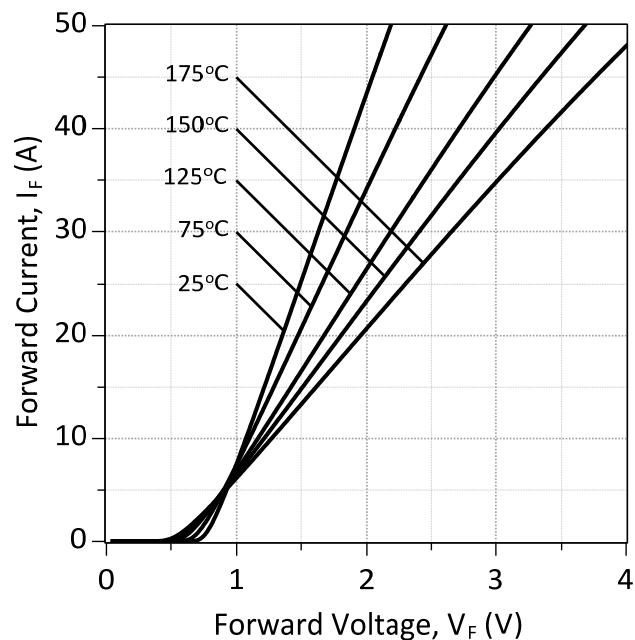
| Parameter               | Symbol         | Conditions  | Values                  |      |      | Unit |
|-------------------------|----------------|---|-------------------------|------|------|------|
|                         |                |   | Min.                    | Typ. | Max. |      |
| Diode Forward Voltage   | V <sub>F</sub> | I <sub>F</sub> = 25 A, T <sub>j</sub> = 25 °C             | 1.5                     | 1.8  | 1.8  | V    |
|                         |                | I <sub>F</sub> = 25 A, T <sub>j</sub> = 175 °C            | 2.3                     | 2.7  | 2.7  |      |
| Reverse Current         | I <sub>R</sub> | V <sub>R</sub> = 1700 V, T <sub>j</sub> = 25 °C           | 5                       | 30   | 30   | μA   |
|                         |                | V <sub>R</sub> = 1700 V, T <sub>j</sub> = 175 °C          | 151                     | 981  | 981  |      |
| Total Capacitive Charge | Q <sub>C</sub> | I <sub>F</sub> ≤ I <sub>F,MAX</sub>                       | V <sub>R</sub> = 600 V  | 71   | 71   | nC   |
|                         |                | dI <sub>F</sub> /dt = 200 A/μs                            | V <sub>R</sub> = 1200 V | 103  | 103  |      |
| Switching Time          | t <sub>s</sub> | T <sub>j</sub> = 175 °C                                   | V <sub>R</sub> = 600 V  | < 10 | < 10 | ns   |
|                         |                |   | V <sub>R</sub> = 1200 V |      |      |      |
| Total Capacitance       | C              | V <sub>R</sub> = 1 V, f = 1 MHz, T <sub>j</sub> = 25°C    | 1596                    | 1596 | 1596 | pF   |
|                         |                | V <sub>R</sub> = 1700 V, f = 1 MHz, T <sub>j</sub> = 25°C | 73                      | 73   | 73   |      |

## Thermal / Mechanical Characteristics

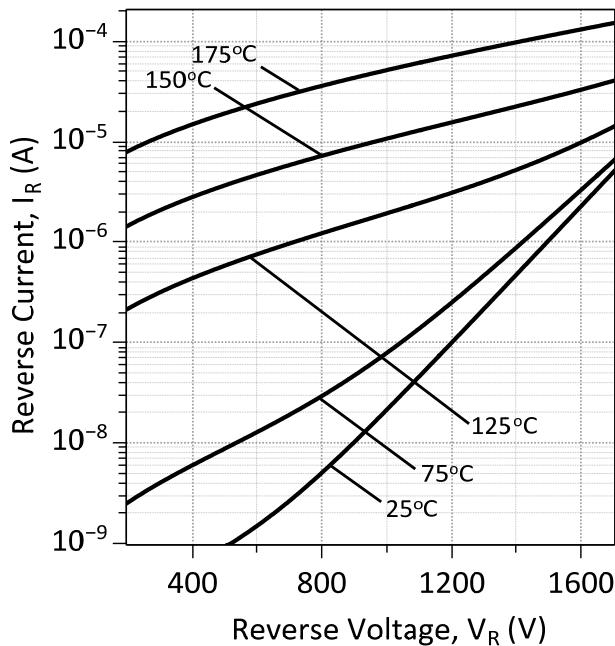
|                                     |                   |      |      |
|-------------------------------------|-------------------|------|------|
| Thermal Resistance, Junction - Case | R <sub>thJC</sub> | 0.15 | °C/W |
| Weight                              | W <sub>T</sub>    | 6    | g    |
| Mounting Torque                     | T <sub>M</sub>    | 1.1  | Nm   |

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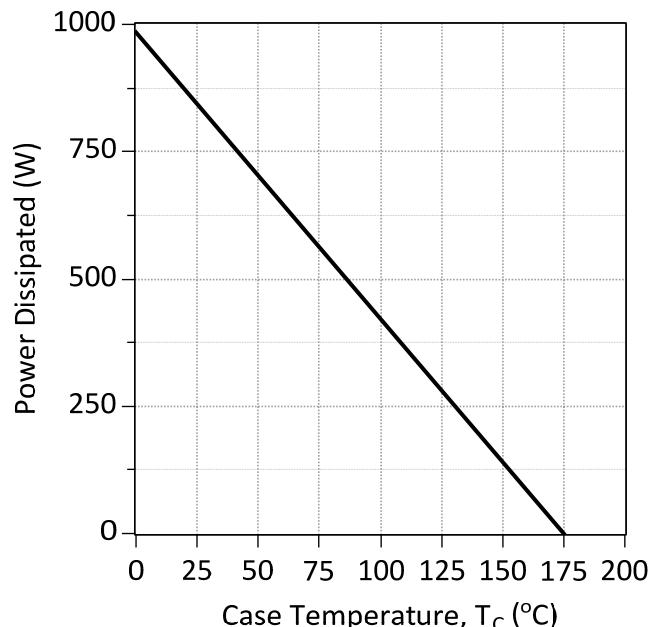
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$$I_F = f(V_F, T_j); t_P = 10 \mu\text{s}$$

**Figure 1: Typical Forward Characteristics**

$$I_R = f(V_R, T_j)$$



$$P_{tot} = f(T_C)$$

**Figure 2: Typical Reverse Characteristics****Figure 3: Power Derating Curve**

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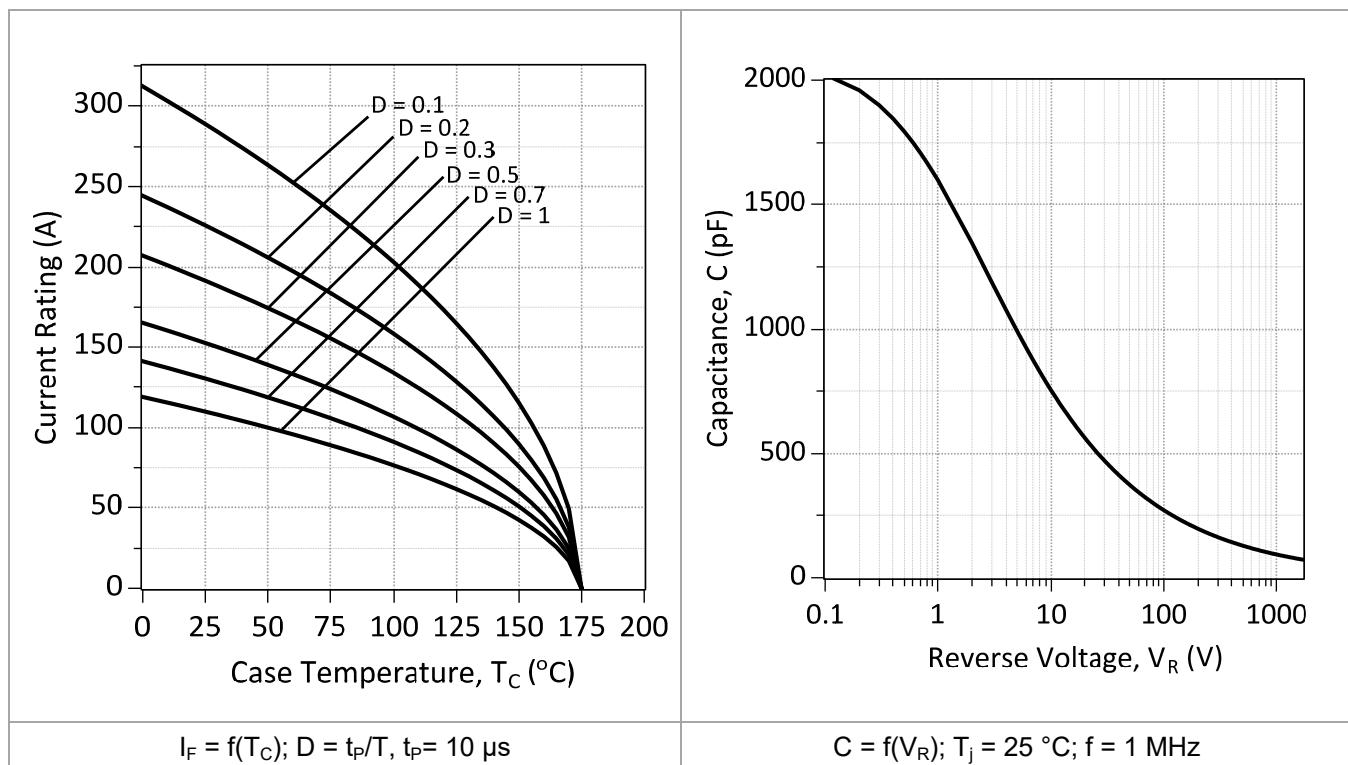


Figure 4: Current Derating Curves

Figure 5: Typical Junction Capacitance vs Reverse Voltage Characteristics

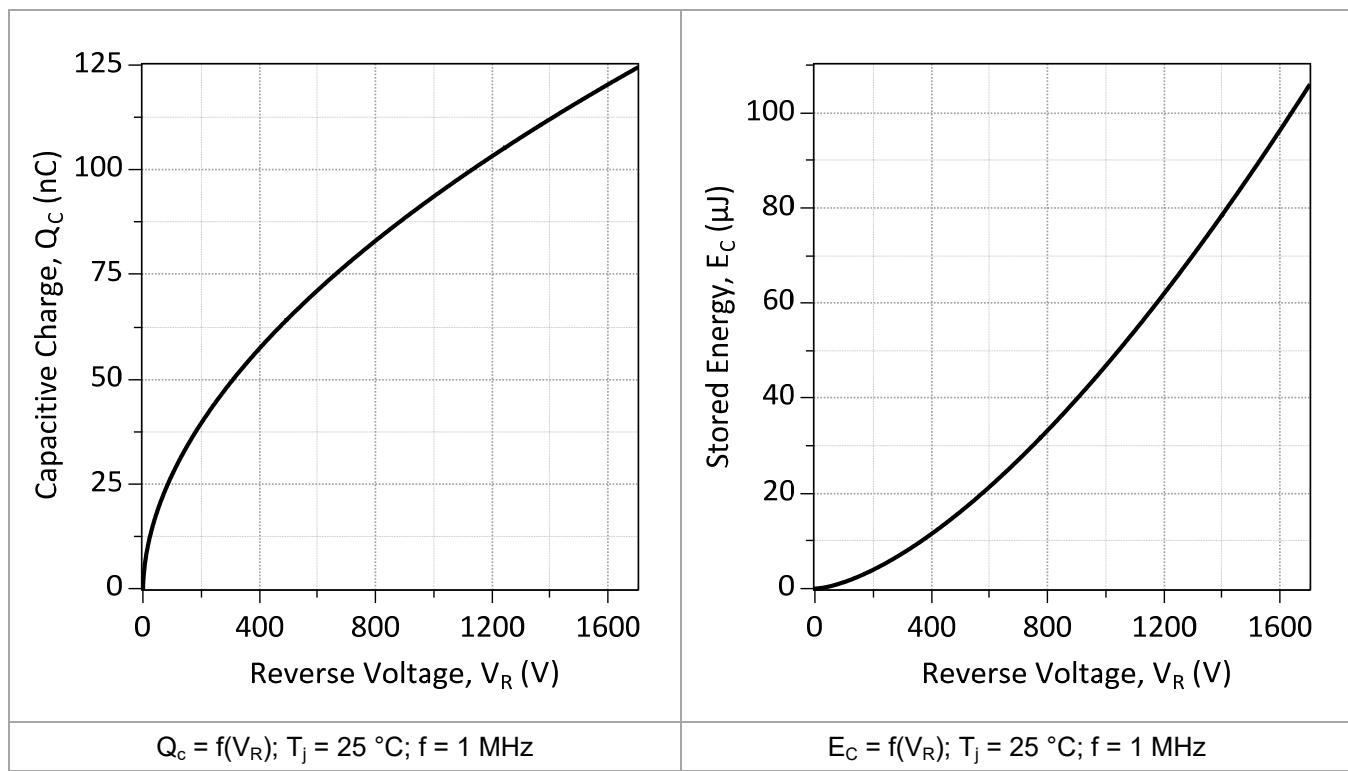


Figure 6: Typical Capacitive Charge vs Reverse Voltage Characteristics

Figure 7: Typical Capacitive Energy vs Reverse Voltage Characteristics



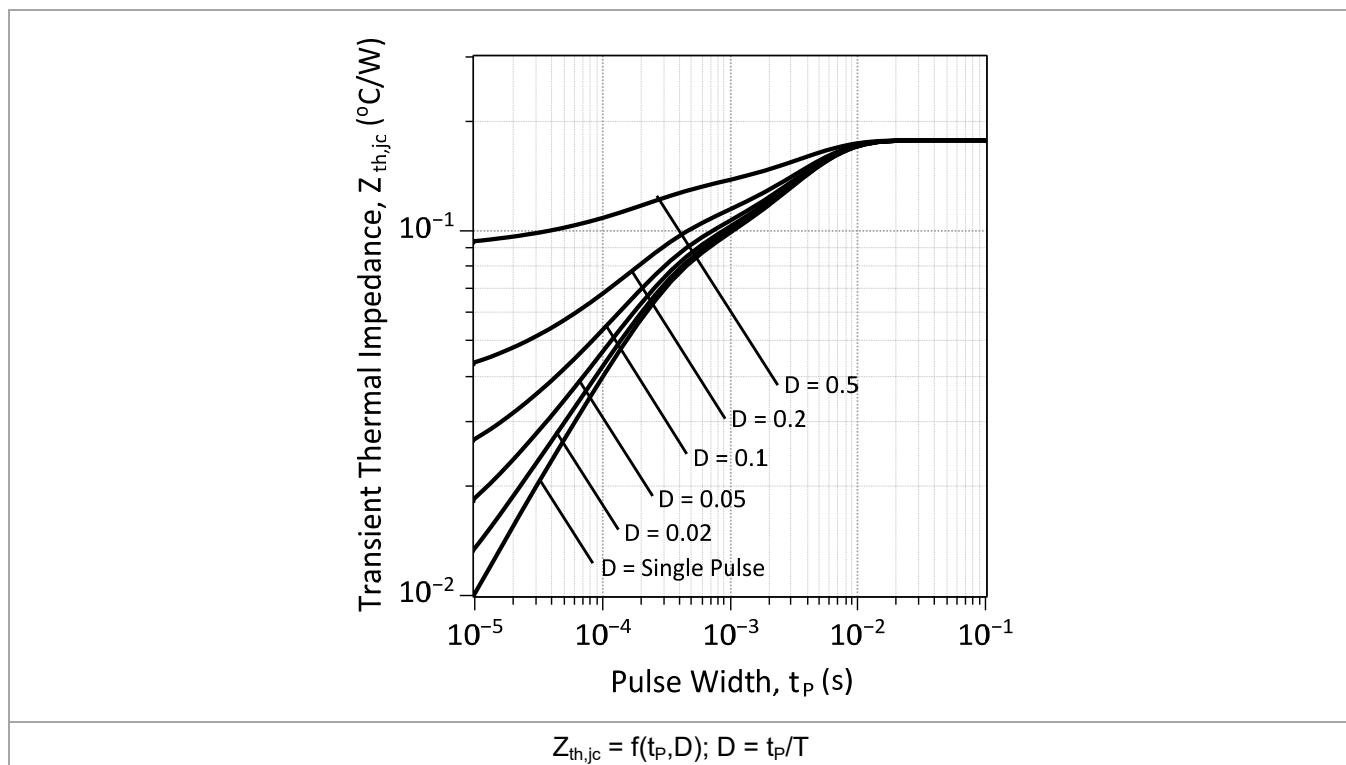
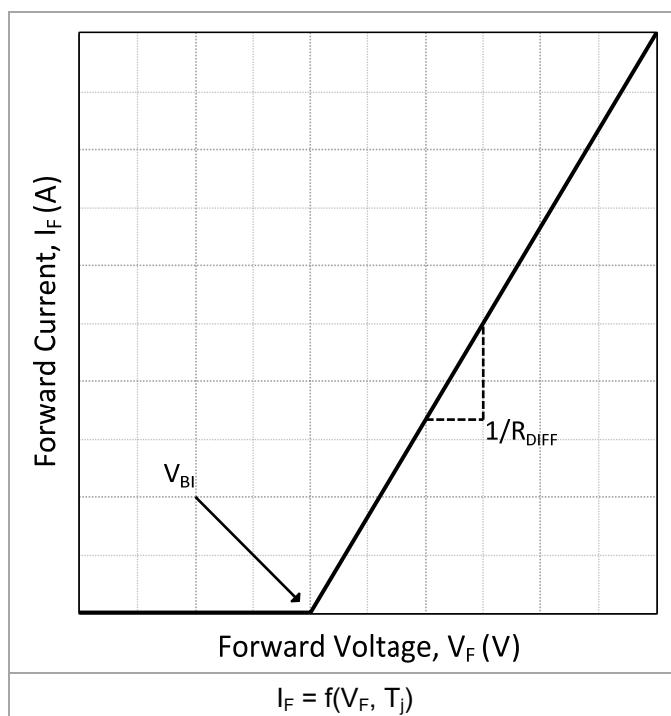


Figure 8: Transient Thermal Impedance



$$I_F = (V_F - V_{BI})/R_{DIFF} \text{ (A)}$$

**Built-In Voltage ( $V_{BI}$ ):**

$$V_{BI}(T_j) = m * T_j + n \text{ (V)}$$

$$m = -1.93e-03, n = 0.86$$

**Differential Resistance ( $R_{DIFF}$ ):**

$$R_{DIFF}(T_j) = a * T_j^2 + b * T_j + c \text{ (\Omega)}$$

$$a = 8.10e-07, b = 9.76e-05, c = 0.0232$$

Figure 9: Forward Curve Model

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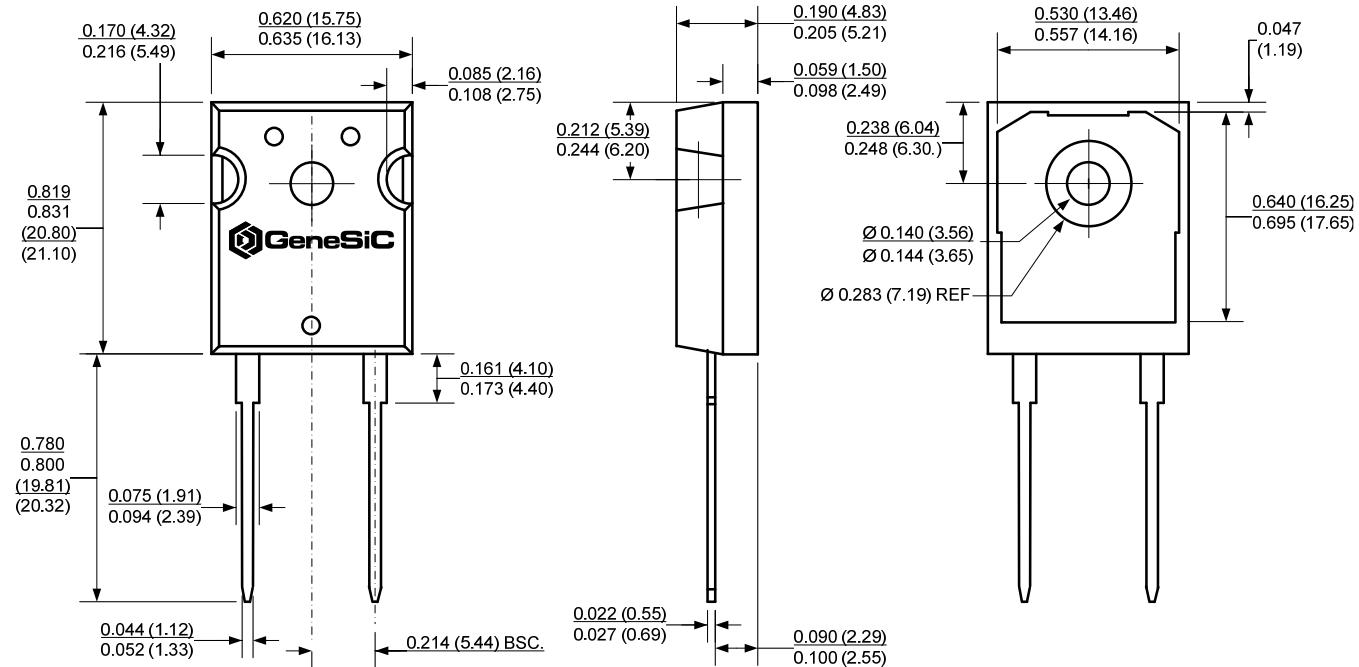
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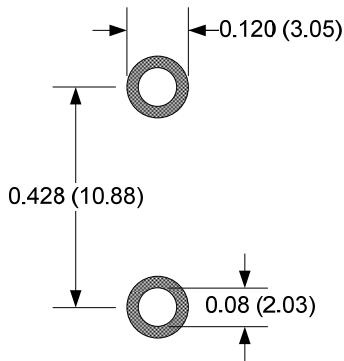
## Package Dimensions

TO-247-2L

Package Outline



## Recommended Solder Pad Layout



### NOTE

1. CONTROLLED DIMENSION IS INCH. DIMENSION IN BRACKET IS MILLIMETER.
2. DIMENSIONS DO NOT INCLUDE END FLASH, MOLD FLASH, MATERIAL PROTRUSIONS

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## **RoHS Compliance**

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented November 15, 2017. RoHS Declarations for this product can be obtained from your GeneSiC representative.

## **REACh Compliance**

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a GeneSiC representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control systems.

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## **Related Links**

- Soldering Document: <http://www.genesicsemi.com/quality/quality-manual/>
- Tin-whisker Report: <http://www.genesicsemi.com/quality/compliance/>
- Reliability Report: <http://www.genesicsemi.com/quality/reliability/>